

SPECIFICATIONS

CLAB50GT2R2W



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLAB50GT2R2W	InGaN/InGaAIP	Green/Red	White Diffused	40°



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ABSOLUTE MAXIMUM RATINGS

Parameter Symbol Max Rating Unit 100 **Power Dissipation** PD mW 60 **Pulse Current Forward Current** IFP mA 30 **Continuous Forward Current** IF mΑ V **Reverse Voltage** VR 5 **Operating Temperature Range** TOPR -25~+85 °C Storage Temperature Range °C Tstg -30~+85

IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

Value Test Condi-Parameter Symbol Color Unit tion Min Тур Max Red 150 250 _ Luminous Intensity I_F = 20mA IV mcd Green 1300 1000 Red 2.1 2.4 _ **Forward Voltage** VF I⊧ = 20mA V 3.4 Green 3.1 _ Red 10 _ _ **Reverse Leakage Current** $V_R = 5V$ IR μA Green 10 _ _ Red 40 _ _ $2\theta 1/2$ I⊧ = 20mA Viewing Angle deg Green 40 _ _ 620 630 Red _ **Dominant Wavelength** I⊧ = 20mA λD nm 520 530 Green _

*Tolerance of viewing angle: -10 / +5 deg.



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(TA=25°C)

(TA=25°C)



OPTICAL CHARACTERISTIC CURVES



Forward Current vs. Relative Luminous Intensity



Forward Current vs. Ambient Temperature



Forward Current (mA)

Relative Luminous Intensity vs. Ambient Temperature



Relative Luminous Intensity vs. Main Wavelength



Dominant Wavelength (nm)

Radiation Diagram





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SOLDERING CONDITIONS – LAMP TYPE LED

* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

* Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering					
Temperature Soldering Time	3mm Series	Others			
	300 °C Max	350 °C Max			
	3 Second Max	3 Second Max			
FOSILION	No closer than 3mm from the	No closer than 3mm from the			
	base of the epoxy	base of the epoxy			

* Do not apply any stress to the lead. Particularly when heated.

- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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